

March 2010

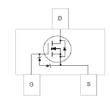
2N7002K

N-Channel Enhancement Mode Field Effect Transistor

Features

- Low On-Resistance
- · Low Gate Threshold Voltage
- · Low Input Capacitance
- · Fast Switching Speed
- Low Input/Output Leakage
- · Ultra-Small Surface Mount Package
- Pb Free/RoHS Compliant
- ESD HBM=2000V (Typical:3000V) as per JESD22 A114 and ESD CDM=2000V as per JESD22 C101





Absolute Maximum Ratings * T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V _{DSS}	Orain-Source Voltage 60		V	
V_{DGR}	Drain-Gate Voltage $R_{GS} \le 1.0 M\Omega$ 60		V	
V_{GSS}	Gate-Source Voltage ±20		V	
I _D	Drain Current Continuous Pulsed	300 800	mA	
T_J	Operating Junction Temperature Range	-55 to +150	°C	
T _{STG}	Storage Temperature Range	-55 to +150	°C	

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may by impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
P _D	Total Device Dissipation Derating above T _A = 25°C	350 2.8	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient *	350	°C/W

^{*} Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch. Minimum land pad size

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Electrical Characteristics $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Test Condition	MIN	MAX	Units		
Off Char	Off Characteristics (Note1)						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D =10uA	60		V		
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 60V, V _{GS} = 0V V _{DS} = 60V, V _{GS} = 0V, @T _C = 125°C		1.0 500	μА		
I _{GSS}	Gate-Body Leakage	V_{GS} = ±20V, V_{DS} = 0V		±10	μΑ		
On Char	On Characteristics (Note1)						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250uA$	1.0	2.5	V		
R _{DS(ON)}	Satic Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 0.5A$ $V_{GS} = 4.5V, I_D = 200mA$		2 4	Ω		
I _{D(ON)}	On-State Drain Current	V _{GS} = 10V, V _{DS} = 7.5V V _{GS} = 4.5V, V _{DS} = 10V	1.5 1.2		А		
9 _{FS}	Forward Transconductance	$V_{DS} = 10V, I_D = 0.2A$	200		mS		
Dynamic	Dynamic Characteristics						
C _{iss}	Input Capacitance			50	pF		
C _{oss}	Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$		15	pF		
C _{rss}	Reverse Transfer Capacitance			6	pF		
Switchin	Switching Characteristics						
t _{D(ON)}	Turn-On Delay Time	$V_{DD} = 30V, I_{DSS} = 200 \text{mA},$		5	nc		
t _{D(OFF)}	Turn-Off Delay Time	$R_G = 10\Omega$, $V_{GS} = 10V$		30	ns		

Note1: Short duration test pulse used to minimize self-heating effect.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

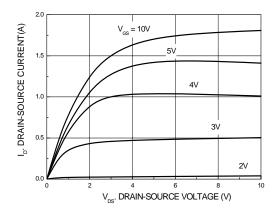


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current

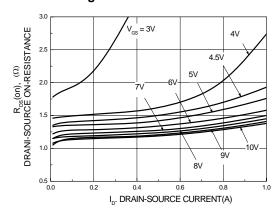


Figure 3. On-Resistance Variation with Temperature

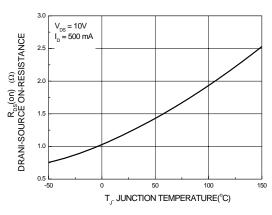


Figure 4. On-Resistance Variation with Gate-Source Voltage

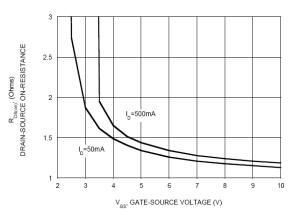


Figure 5. Transfer Characteristics

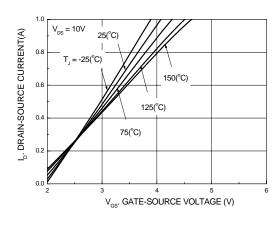
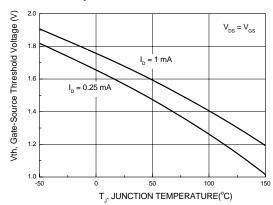


Figure 6. Gate Threshold Variation with Temperature

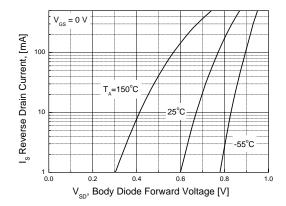


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Typical Performance Characteristics (Continue)

Figure 7. Reverse Drain Current Variation with Diode Forward Voltage and Temperature



Physical Dimensions SOT-23 0.95 2.92±0.20 1.30+0.20 2.20 (0.29)-1.00 ⊕ 0.20 M A B 0.95 -1.90 1.90 LAND PATTERN RECOMMENDATION SEE DETAIL A -1.30 MAX (0.93)△ 0.10 M C 2.40±0.30 GAGE PLANE NOTES: UNLESS OTHERWISE SPECIFIED REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H. ALL DIMENSIONS ARE IN MILLIMETERS. DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS. DIMENSIONING AND TOLERANCING PER ASME Y14.5M — 1994. DRAWING FILE NAME: MAO3DREV9 0.20 MIN SEATING PLANE DETAIL A Dimensions in Millimeters



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Definition of Terms				
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